12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20260604000.2A
Qualify additional BOM material for select package devices
Change Notification / Sample Request

Date: June 19, 2026
To: MOUSER PCN

Dear Customer:

The purpose of this version A is to retract select devices from this change notification. These devices were inadvertently included and is not affected by this change.

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20260604000.2A
Change Notification / Sample Request
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records**,** you have recently purchased these devices**.** The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
ISO6741FQDWRQ1	NULL
ISO6761FQDWRQ1	NULL
ISO6763FQDWRQ1	NULL
ISO7741FQDWRQ1	ISO7741FQDWRQ1
ISO6762FQDWRQ1	NULL
ISO7740QDWRQ1	NULL
ISO6762QDWRQ1	NULL
ISO6742FQDWRQ1	NULL
ISO7760FQDWRQ1	NULL
ISO6741QDWRQ1	NULL
ISO7730FQDWRQ1	NULL
ISO7762FQDWRQ1	NULL
ISO7720QDWVRQ1	NULL
ISO7721FQDWVRQ1	NULL
ISO7740FQDWRQ1	NULL
ISO7721FQDWRQ1	NULL
ISO7763QDWRQ1	NULL
ISO7763FQDWRQ1	NULL
ISO7730QDWRQ1	NULL
ISO7720FQDWVRQ1	NULL
ISO7731QDWRQ1	ISO7731QDWRQ1
ISO7710FQDWRQ1	NULL
ISO7742FQDWRQ1	NULL
ISO7720QDWRQ1	NULL
ISO7742QDWRQ1	NULL
ISO6720QDWVRQ1	NULL
ISO6721QDWVRQ1	NULL
ISO7721QDWVRQ1	NULL
ISO7731FQDWRQ1	ISO7731FQDWRQ1
ISO7762QDWRQ1	NULL
ISO6720FQDWVRQ1	NULL
ISO6721FQDWVRQ1	NULL
ISO7761QDWRQ1	ISO7761QDWRQ1
ISO7741QDWRQ1	ISO7741QDWRQ1

Technical details of this Product Change follow on the next page(s).

PCN Number:	20260604000.2A	**PCN Date:**	June 19, 2026
Title:	Qualify additional BOM material for select package devices		
Customer Contact:	Change Management team	**Dept:**	Quality Services
Proposed 1st Ship Date:	December 16, 2026	**Sample requests accepted until:**	August 18, 2026

***Sample requests received after** August 18, 2026 **will not be supported.**

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Material
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☐	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Material
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process

PCN Details

Description of Change:

Revision A is to remove select devices in the Product Affected Section (with ~~strikethrough~~) and highlighted in yellow. These devices were inadvertently added and not affected by this change.

Texas Instruments is pleased to announce the qualification of additional BOM material for select devices in the SOIC package. Device affected will remain on current Assembly & Test sites. Material differences as follows.

	Current	Additional
Mold compound	4221499-0008	4221499-1008

Reason for Change:

Continuity of supply.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

Review the SDP for full evaluation of the change based on the customer use case.

Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

None

Product Affected:

UCC21520QDWRQ1	~~ISO7761QDWRQ1~~	UCC21755QDWRQ1
~~ISO7763FQDWRQ1~~	AMC1305L25QDWQ1	AMC1305M05QDWQ1
~~ISO7742FQDWRQ1~~	UCC21551AQDWRQ1	AMC1304L05QDWRQ1
~~ISO6740QDWRQ1~~	UCC21520AQDWRQ1	UCC21739QDWRQ1
ISO1042BQDWRQ1	SNA21750QDWRQ1	~~ISO7730FQDWRQ1~~
~~ISO6760QDWRQ1~~	UCC5350MCQDRQ1	UCC21550AQDWRQ1
UCC21540QDWKRQ1	~~ISO7762QDWRQ1~~	~~ISO7740QDWRQ1~~
~~ISO7721QDWVRQ1~~	~~ISO6720FQDWVRQ1~~	SN5350MCQDRQ1
UCC23513BQDWYRQ1	ISO5852SQDWRQ1	~~ISO7741QDWRQ1~~
ISO5452QDWRQ1	UCC23513QDWYRQ1	~~ISO7740FQDWRQ1~~
~~ISO6760FQDWRQ1~~	AMC1305L25QDWRQ1	ISO1640QDWRQ1

ISO1042BQDWVQ1	UCC21550AQDWKRQ1	~~ISO7742QDWRQ1~~
~~ISO6762FQDWRQ1~~	~~ISO7731FQDWRQ1~~	AMC1305M25QDWRQ1
~~ISO7721QDWRQ1~~	AMC1336QDWVRQ1	~~ISO7721FQDWRQ1~~
~~ISO7760QDWRQ1~~	UCC21320QDWKRQ1	~~ISO6731QDWRQ1~~
AMC1304L25QDWQ1	~~ISO6742QDWRQ1~~	UCC5320SCDWVR
~~ISO7760FQDWRQ1~~	UCC21756QDWRQ1	AMC1304M05QDWQ1
ISO5851QDWRQ1	~~ISO6763FQDWRQ1~~	UCC21732QDWRQ1
~~ISO6721FQDWVRQ1~~	~~ISO7731QDWRQ1~~	ISO1042QDWQ1
SN21540QDWKRQ1	~~ISO6721QDWVRQ1~~	UCC23313QDWYRQ1
UCC21759QDWRQ1	AMC1304M25QDWRQ1	AMC1301QDWVRQ1
~~ISO7720QDWRQ1~~	UCC21551AQDWKRQ1	SN21750QDWRQ1
UCC23511QDWYRQ1	AMC1204QDWRQ1	~~ISO7720QDWVRQ1~~
UCC23313BQDWYRQ1	~~ISO6740FQDWRQ1~~	UCC21550BQDWRQ1
AMC1305M25QDWQ1	~~ISO7762FQDWRQ1~~	SNA21222QDRQ1
AMC1311CQDWVRQ1	~~ISO7710QDWRQ1~~	AMC1200TDWVRQ1
~~ISO7763QDWRQ1~~	ISO1042QDWVRQ1	ISO5451QDWRQ1
UCC21222QDRQ1	~~ISO7761FQDWRQ1~~	~~ISO6741QDWRQ1~~
AMC1305M05QDWRQ1	UCC21737QDWRQ1	~~ISO6720QDWVRQ1~~
UCC21717QDWRQ1	AMC1301QDWVQ1	~~ISO6741FQDWRQ1~~
ISO1042BQDWQ1	AMC1300QDWVRQ1	SN21710QDWRQ1
~~ISO6762QDWRQ1~~	~~ISO7720FQDWRQ1~~	AMC1304L25QDWRQ1
AMC1304M25QDWQ1	~~ISO6731FQDWRQ1~~	~~ISO7730QDWRQ1~~
~~ISO6742FQDWRQ1~~	~~ISO6761QDWRQ1~~	~~ISO6763QDWRQ1~~
~~ISO7720FQDWVRQ1~~	~~ISO7710FQDWRQ1~~	AMC1304L05QDWQ1
~~ISO6761FQDWRQ1~~	~~ISO7741FQDWRQ1~~	AMC1304M05QDWRQ1
~~ISO7721FQDWVRQ1~~	UCC21550BQDWKRQ1	

Qualification Data

Automotive Qualification Summary

(As per AEC-Q100 Rev. J and JEDEC Guidelines)

Approve Date 09-October-2025

Product Attributes

Attributes	Qual Device: ISO1410DWR	QBS Process Reference: ISO5851QDWQ1	QBS Package Reference: ISOUSB211DPRQ1
Automotive Grade Level	Grade 1	Grade 1	Grade 1
Operating Temp Range (C)	-40 to 125	-40 to 125	-40 to 125
Product Function	Power Management	Interface	Interface
Wafer Fab Supplier	MH8, MH8, MH8	MH8, DP1DM5, DP1DM5	MH8, MH8, RFAB, RFAB, MH8, MH8
Assembly Site	TAI	TAI	TAI
Package Group	SOIC	SOIC	SSOP
Package Designator	DW	DW	DP
Pin Count	16	16	28

QBS: Qual By Similarity, also known as Generic Data
Qual Device ISO1410DWR is qualified at MSL2 260C
Qual Device UCC5871QDWJRQ1 is qualified at MSL3 260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: ISO1410DWR	QBS Process Reference: ISO5851QDWQ1	QBS Package Reference: ISOUSB211DPRQ1
Test Group A - Accelerated Environment Stress Tests										
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL2 260C	-	No Fails	-	No Fails
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Autoclave	121C/15psig	96 Hours	3/231/0	-	3/231/0
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	-	3/231/0
TC-BP	A4	MIL-STD883 Method 2011	1	5	Post Temp Cycle Bond Pull	-	-	-	-	1/5/0
TC-SAM	A4	-	3	3	Post TC SAM	<50% delamination	-	-	-	3/36/0
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	150C	1000 Hours	-	-	3/135/0
Test Group B - Accelerated Lifetime Simulation Tests										
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	125C	1000 Hours	-	3/231/0	1/77/0
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate	125C	48 Hours	-	3/2400/0	-
Test Group C - Package Assembly Integrity Tests										
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	3/90/0	-	3/90/0

WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	3/90/0	-	3/90/0
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	-	-	1/15/0
PD	C4	JEDEC JESD22-B100 and B108	3	10	Physical Dimensions	Cpk>1.67	-	3/30/0	-	3/30/0
Test Group D - Die Fabrication Reliability Tests										
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
TDDB	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
Test Group E - Electrical Verification Tests										
ESD	E2	AEC Q100-002	1	3	ESD HBM	-	2000 Volts	-	1/3/0	-
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	500 Volts	-	1/3/0	-
LU	E4	AEC Q100-004	1	3	Latch-Up	Per AEC Q100-004	-	-	1/6/0	-
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	1/30/0	-

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Ambient Operating Temperature by Automotive Grade Level:
Grade 0 (or E): -40C to +150C
Grade 1 (or Q): -40C to +125C
Grade 2 (or T): -40C to +105C
Grade 3 (or I) : -40C to +85C
E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):
Room/Hot/Cold : HTOL, ED
Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU
Room : AC/uHAST
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2503-064

Automotive Qualification Summary
(As per AEC and JEDEC Guidelines)

Q006 SOIC, SSOP
Approve Date 09-October-2025

Product Attributes

Attributes	Qual Device: ISO1410DWR	QBS Package Reference: ISOUSB211DPRQ1
Automotive Grade Level	Grade 1	Grade 1
Operating Temp Range (C)	-40 to 125	-40 to 125
Product Function	Power Management	Interface
Wafer Fab Supplier	MH8, MH8, MH8	MH8, MH8, RFAB, RFAB, MH8, MH8
Assembly Site	TAI	TAI
Package Group	SOIC	SSOP
Package Designator	DW	DP
Pin Count	16	28

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: ISO1410DWR	QBS Reference: ISOUSB211DPRQ1
Test Group A - Accelerated Environment Stress Tests									
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL2 260C	-	No Fails	No Fails
PC	A1.1	-	3	22	SAM Precon Pre	Review for delamination	-	3/66/0	3/66/0
PC	A1.2	-	3	22	SAM Precon Post	Review for delamination	-	3/66/0	3/66/0
HAST	A2.1	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	-	3/231/0
HAST	A2.1.2	-	3	1	Cross Section, post bHAST, 1X	Post stress cross section	Completed	-	3/3/0
HAST	A2.1.3	-	3	3	Wire Bond Shear, post bHAST, 1X	Post stress	-	-	3/9/0
HAST	A2.1.4	-	3	3	Bond Pull over Stitch, post bHAST, 1X	Post stress	-	-	3/9/0
HAST	A2.1.5	-	3	3	Bond Pull over Ball, post bHAST, 1X	Post stress	-	-	3/9/0
HAST	A2.2	JEDEC JESD22-A110	3	70	Biased HAST	130C/85%RH	192 Hours	-	3/210/0
HAST	A2.2.1	-	3	22	SAM Analysis, post bHAST 2X	Review for delamination	Completed	-	3/66/0
HAST	A2.2.2	-	3	1	Cross Section, post bHAST, 2X	Post stress cross section	Completed	-	3/3/0
HAST	A2.2.3	-	3	3	Wire Bond Shear, post bHAST, 2X	Post stress	-	-	3/9/0
HAST	A2.2.4	-	3	3	Bond Pull over Stitch, post bHAST, 2X	Post stress	-	-	3/9/0
HAST	A2.2.5	-	3	3	Bond Pull over Ball, post bHAST, 2X	Post stress	-	-	3/9/0
TC	A4.1	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	3/231/0
TC	A4.1.1	-	3	22	SAM Analysis, post TC 1X	Review for delamination	Completed	3/66/0	3/66/0

TC	A4.1.2	-	3	1	Cross Section, post TC, 1X	Post stress cross section	Completed	3/3/0	3/3/0
TC	A4.1.3	-	3	3	Wire Bond Shear, post TC, 1X	Post stress	-	3/9/0	3/9/0
TC	A4.1.4	-	3	3	Bond Pull over Stitch, post TC, 1X	Post stress	-	3/9/0	3/9/0
TC	A4.1.5	-	3	3	Bond Pull over Ball, post TC, 1X	Post stress	-	3/9/0	3/9/0
TC	A4.2	JEDEC JESD22-A104 and Appendix 3	3	70	Temperature Cycle	-65C/150C	1000 Cycles	3/210/0	3/210/0
TC	A4.2.1	-	3	22	SAM Analysis, post TC, 2X	Review for delamination	Completed	3/66/0	3/66/0
TC	A4.2.2	-	3	1	Cross Section, post TC, 2X	Post stress cross section	Completed	3/3/0	3/3/0
TC	A4.2.3	-	3	3	Wire Bond Shear, post TC, 2X	Post stress	-	3/9/0	3/9/0
TC	A4.2.4	-	3	3	Bond Pull over Stitch, post TC, 2X	Post stress	-	3/9/0	3/9/0
TC	A4.2.5	-	3	3	Bond Pull over Ball, post TC, 2X	Post stress	-	3/9/0	3/9/0
HTSL	A6.1	JEDEC JESD22-A103	3	45	High Temperature Storage Life	150C	1000 Hours	-	3/135/0
HTSL	A6.1.1	-	3	1	Cross Section, post HTSL, 1X	Post stress cross section	Completed	-	3/3/0
HTSL	A6.2	JEDEC JESD22-A103	3	44	High Temperature Storage Life	150C	2000 Hours	-	3/132/0
HTSL	A6.2.1	-	3	1	Cross Section, post HTSL, 2X	Post stress cross section	Completed	-	3/3/0
Test Group C - Package Assembly Integrity Tests									
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	3/90/0	3/90/0
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	3/90/0	3/90/0

QBS: Qual By Similarity, also known as Generic Data
Qual Device ISO1410DWR is qualified at MSL2 260C
Qual Device UCC5871QDWJRQ1 is qualified at MSL3 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
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Grade 2 (or T): -40C to +105C
Grade 3 (or I) : -40C to +85C
E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):
Room/Hot/Cold : HTOL, ED
Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU
Room : AC/uHAST
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2503-064

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a ‘product qualification family’ for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled “QBS

Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

ZVEI ID: SEM-PA-11

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.